

Silicon Carbide Schottky Diode G4 MPS Technology

Features

- New Thin Wafer Technology
- Low Forward Voltage Drop (V_F)
- Zero Reverse Recovery Current
- Zero Forward Recovery Voltage
- Positive Temperature Coefficient on V_F
- Temperature-independent Switching

V_{RRM}	=	650	V
I_F ($T_c \leq 135^\circ C$)	=	19	A
Q_C	=	25	nC

Benefits

- Replace Bipolar with Unipolar Device
- Reduction of Heat Sink Size
- Parallel Devices Without Thermal Runaway
- Essentially No Switching Losses

Package



TO-220-2



Applications

- Switch Mode Power Supplies
- Uninterruptible Power Supplies
- Server/Telecom Power Supplies
- Industrial Power Supplies

Device Marking	Device	Device Package	Packaging Code	Tube (PCS)
SC06510	SC4S06510A	TO-220-2	-C	50

Maximum Ratings

Symbol	Parameter	Value	Unit	Test Conditions	Note
V_{RRM}	Repetitive Peak Reverse Voltage	650	V	$T_c = 25^\circ C$	
V_{RSM}	Surge Peak Reverse Voltage	650	V	$T_c = 25^\circ C$	
V_R	DC Blocking Voltage	650	V	$T_c = 25^\circ C$	
I_F	Forward Current	38 19 10	A	$T_c \leq 25^\circ C$ $T_c \leq 135^\circ C$ $T_c \leq 158^\circ C$	
I_{FSM}	Non-Repetitive Forward Surge Current	86	A	$T_c = 25^\circ C, t_p = 8.3ms, \text{Half Sine Wave}$	
P_{tot}	Power Dissipation	150	W	$T_c = 25^\circ C$	Fig.3
T_J, T_{STG}	Operating Junction and Storage Temperature	-55 to 175	°C		
T_{sold}	Soldering Temperature	260	°C		
	TO-220 Mounting Torque	1	Nm	M3 Screw	

Electrical Characteristics

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
V_F	Forward Voltage	1.27 1.38	1.5 1.6	V	$I_F = 10A, T_J = 25^\circ C$ $I_F = 10A, T_J = 175^\circ C$	Fig.1
I_R	Reverse Current	6 25	50 200	μA	$V_R = 650V, T_J = 25^\circ C$ $V_R = 650V, T_J = 175^\circ C$	Fig.2
C	Total Capacitance	640 66 48	/	pF	$V_R = 0.1V, T_J = 25^\circ C, f = 1MHz$ $V_R = 200V, T_J = 25^\circ C, f = 1MHz$ $V_R = 400V, T_J = 25^\circ C, f = 1MHz$	Fig.5
Q_c	Total Capacitive Charge	25	/	nC	$V_R = 400V, I_F = 10A$ $di/dt = 200A/\mu s, T_J = 25^\circ C$	Fig.4

Thermal Characteristics

Symbol	Parameter	Typ.	Unit	Note
$R_{\theta JC}$	Thermal Resistance from Junction to Case	1	$^\circ C/W$	Fig.6
$R_{\theta JA}$	Thermal Resistance from Junction to Ambient	80	$^\circ C/W$	

RATING AND CHARACTERISTICS CURVES(SC4S06510A)

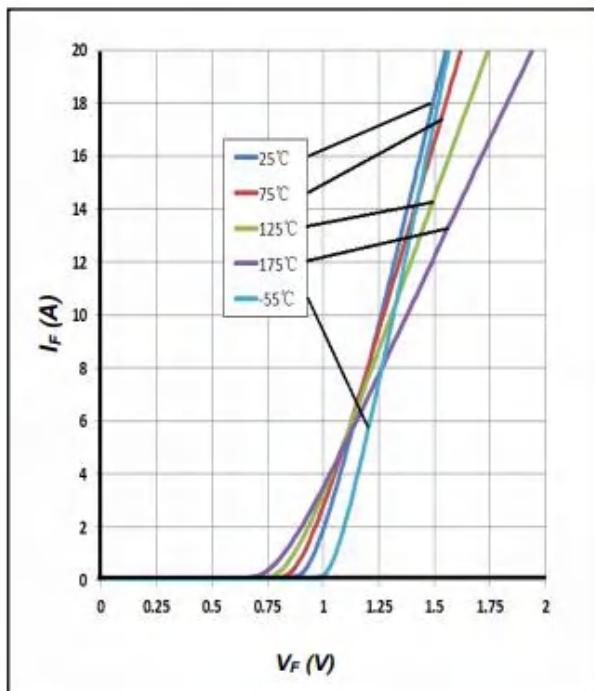


Figure 1. Forward Characteristics

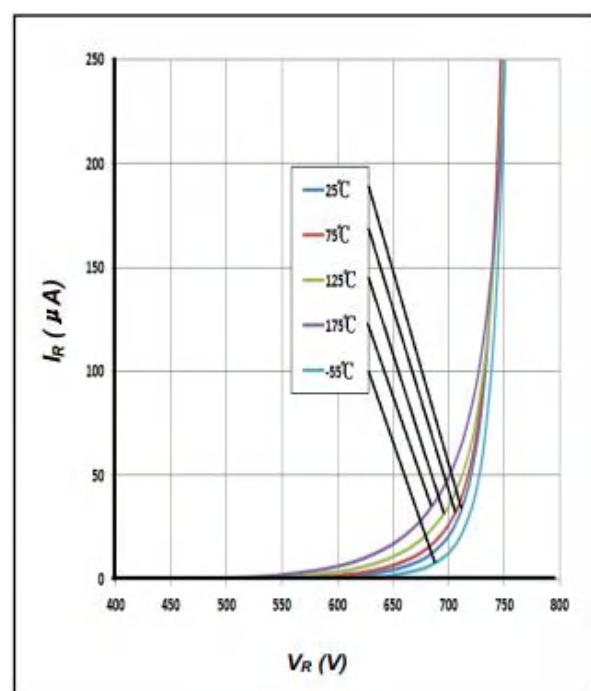


Figure 2. Reverse Characteristics

RATING AND CHARACTERISTICS CURVES (SC4S06510A)

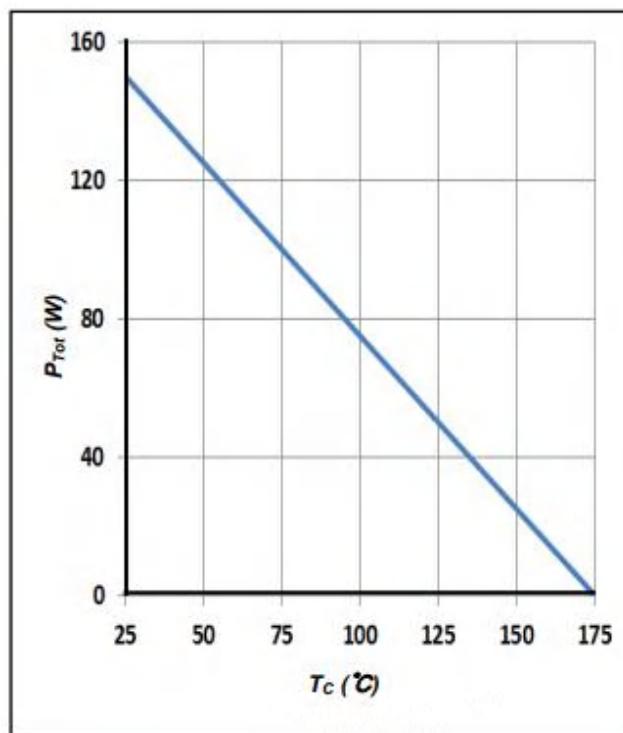


Figure 3. Power Derating

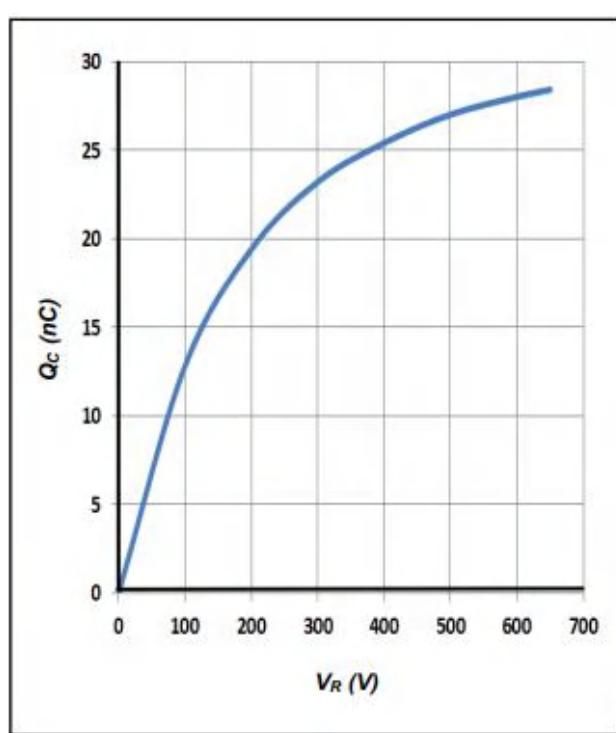


Figure 4. Total Capacitive Charge vs. Reverse Voltage

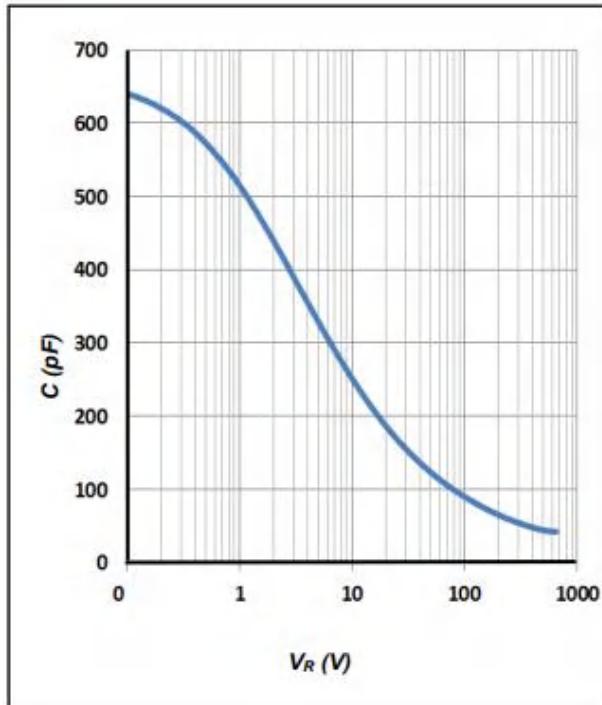


Figure 5. Total Capacitance vs. Reverse Voltage

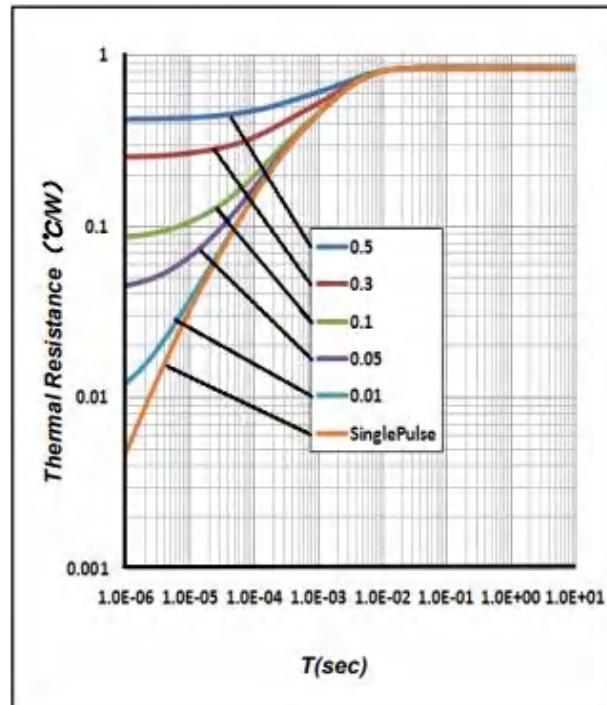
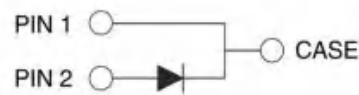
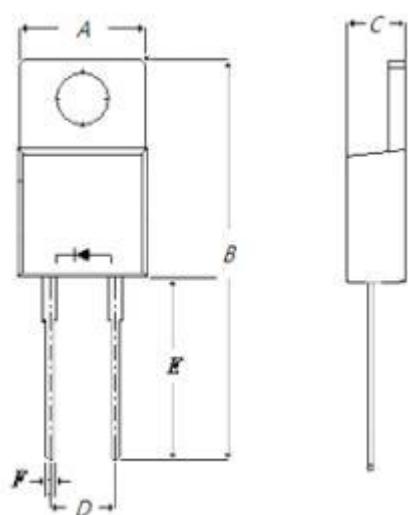


Figure 6. Transient Thermal Impedance

Package Dimensions

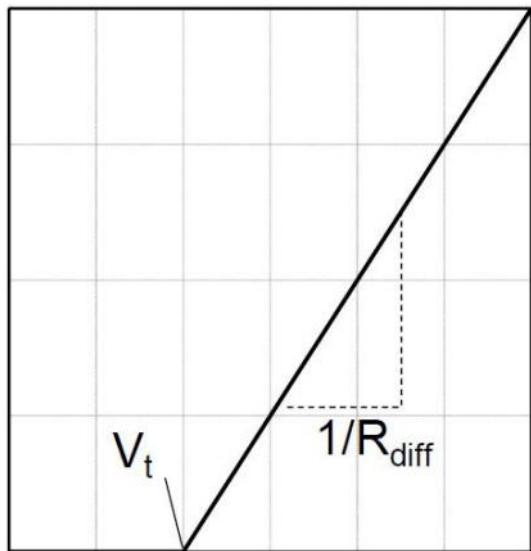
Package TO-220-2



Symbol	Min.(mm)	Typ.(mm)	Max.(mm)
A	9.9	10.2	10.5
B	28	28.7	29.4
C	4.5	4.7	4.9
D	4.9	5.1	5.3
E	13	13.55	14.1
F	0.7	0.81	0.92

Simplified Diode Model

Equivalent IV Curve for Model



$$V_F = V_t + I_F \times R_{diff}$$

$$V_t = -0.00093 \times T_j + 0.92 \text{ [V]}$$

$$R_{diff} = 2 \times 10^{-6} \times T_j^2 - 4.77 \times 10^{-5} \times T_j + 0.055 \text{ [\Omega]}$$

Note:

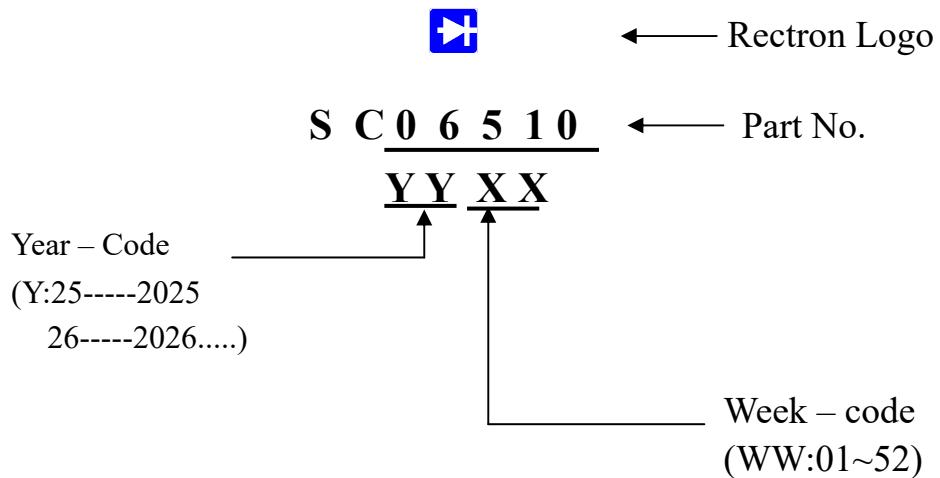
T_j = Diode Junction Temperature In Degrees Celsius,
valid from 25°C to 175°C

I_F = Forward Current
Less than 20A



RECTRON

Marking on the body



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